

3. (Twice Amended) The ceramic heater to be used in semiconductor industry according to claim 1, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

4. (Twice Amended) The ceramic heater to be used in semiconductor industry according to claim 1, wherein said insulating covering comprises oxide glass.

5. (Twice Amended) The ceramic heater to be used in semiconductor industry according to claim 1, wherein said insulating covering comprises a heat resistant resin material.

6. (Amended) The ceramic heater to be used in semiconductor industry according to claim 5, wherein said heat resistant resin material is one or more selected from a polyimide resin and a silicone resin.

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7. (Twice Amended) The ceramic heater to be used in semiconductor industry according to claim 1, wherein the opposite side to the side where said resistance heating element is formed is a heating surface.

8. (Twice Amended) The ceramic heater to be used in semiconductor industry according to claim 1, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

9. (Amended) The ceramic heater to be used in semiconductor industry according to claim 2, wherein said ceramic substrate comprises a nitride ceramic or a carbide ceramic.

10. (Amended) The ceramic heater to be used in semiconductor industry according to claim 2, wherein said insulating covering comprises oxide glass.

11. (Amended) The ceramic heater to be used in semiconductor industry according to claim 3, wherein said insulating covering comprises oxide glass.

12. (Amended) The ceramic heater to be used in semiconductor industry according to claim 2, wherein said insulating covering comprises a heat resistant resin material.

13. (Amended) The ceramic heater to be used in semiconductor industry according to claim 3, wherein said insulating covering comprises a heat resistant resin material.

14. (Amended) The ceramic heater to be used in semiconductor industry according to claim 2, wherein the opposite side to the side where said resistance heating element is formed is a heating surface.

15. (Amended) The ceramic heater to be used in semiconductor industry according to claim 3, wherein the opposite side to the side where said resistance heating element is formed is a heating surface.

16. (Amended) The ceramic heater to be used in semiconductor industry according to claim 4, wherein the opposite side to the side where said resistance heating element is formed is a heating surface.

17. (Amended) The ceramic heater to be used in semiconductor industry according to claim 5, wherein the opposite side to the side where said resistance heating element is formed is a heating surface.

18. (Amended) The ceramic heater to be used in semiconductor industry according to claim 6, wherein the opposite side to the side where said resistance heating element is formed is a heating surface.

19. (Amended) The ceramic heater to be used in semiconductor industry according to claim 2, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

20. (Amended) The ceramic heater to be used in semiconductor industry according to claim 3, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

21. (Amended) The ceramic heater to be used in semiconductor industry according to claim 4, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

22. (Amended) The ceramic heater to be used in semiconductor industry according to claim 5, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

23. (Amended) The ceramic heater to be used in semiconductor industry according to claim 6, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.

24. (Amended) The ceramic heater to be used in semiconductor industry according to claim 7, wherein said insulating covering covers the resistance heating element comprising two or more circuits in a lump.--

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Please add new Claims 25-27 as follows:

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25. (New) The ceramic heater to be used in semiconductor industry according to claim 1, wherein said ceramic substrate is thermally coupled to a semiconductor wafer.

26. (New) The ceramic heater to be used in semiconductor industry according to claim 25, wherein:

said ceramic substrate defines at least one through hole, and

said ceramic heater further comprises:

a lifter pin inserted through said through hole, said lifter pin being configured to support said semiconductor wafer at a distance above said ceramic substrate.